

Form PTO-1449 U.S. Department of Commerce, Patent and Trademark Office					Atty Docket No. BDG018		Serial No. 10/646,415	
<b>INFORMATION DISCLOSURE STATEMENT</b> (Use several sheets if necessary)					Applicant Chia-Chung Wang et al.			
					Filing Date 8/22/03		Group Art Unit 2818	
<b>U.S. Patent Documents</b>								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
PD	AA	4,955,523	09/1990	Calomagno et al.	228	179		
↑	AB	4,970,571	11/1990	Yamakawa et al.	357	71		
	AC	4,984,358	01/1991	Nelson	29	830		
	AD	5,074,947	12/1991	Estes et al.	156	307.3		
	AE	5,106,461	04/1992	Volfson et al.	205	125		
	AF	5,116,463	05/1992	Lin et al.	156	653		
	AG	5,137,845	08/1992	Lochon et al.	437	183		
	AH	5,167,992	12/1992	Lin et al.	427	437		
	AI	5,196,371	03/1993	Kulesza et al.	437	183		
	AJ	5,209,817	05/1993	Ahmad et al.	156	643		
	AK	5,237,130	08/1993	Kulesza et al.	174	260		
↓	AL	5,260,234	11/1993	Long	437	203		
PD	AM	5,261,593	11/1993	Casson et al.	228	180.22		
<b>Foreign Patent Documents</b>								
							<b>Translation</b>	
		Document	Date	Country	Class	Subclass	Yes	No
PD	AN	EP 0 718 882 A1	06/1996	European Patent Office	H01L	23/057		
PD	AO	WO 97/38563	10/1997	WIPO	H05K	1/03		
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AP	Markstein et al., "Controlling the Variables in Stencil Printing," Electronic Packaging & Production, February 1997, pp. 48-56.						
PD	AQ	Elenius, "Choosing a Flip Chip Bumping Supplier - Technology an IC Package contractor should look for," Advanced Packaging, March/April 1998, pp. 70-73.						
Examiner PHUCT-DANG			Date Considered 1/13/05					
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
PD	AA	5,275,330	01/1994	Issacs et al.	228	180.2		
↑	AB	5,284,796	02/1994	Nakanishi et al.	437	183		
↓	AC	5,293,067	03/1994	Thompson et al.	257	668		
↓	AD	5,327,010	07/1994	Uenaka et al.	257	679		
↓	AE	5,334,804	08/1994	Love et al.	174	267		
↓	AF	5,346,750	09/1994	Hatakeyama et al.	428	209		
↓	AG	5,355,283	10/1994	Marrs et al.	361	760		
↓	AH	5,358,621	10/1994	Oyama	205	123		
↓	AI	5,397,921	03/1995	Karnezos	257	779		
↓	AJ	5,407,864	04/1995	Kim	437	203		
↓	AK	5,424,245	06/1995	Gurtler et al.	437	183		
↓	AL	5,438,477	08/1995	Pasch	361	689		
PD	AM	5,439,162	08/1995	George et al.	228	180.22		
<b>Foreign Patent Documents</b>								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
PD	AN	WO 99/57762	11/1999	WIPO	H01L	23/48		
	AO							
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AP	Erickson, "Wafer Bumping: The Missing Link for DCA," Electronic Packaging & Production, July 1998, pp. 43-46.						
PD	AQ	Kuchenmeister et al., "Film Chip Interconnection Systems Prepared By Wet Chemical Metallization," IEEE publication 0-7803-4526-6/98, June 1998, 5 pages.						
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
PD	AA	5,447,886	09/1995	Rai	437	183		
↑	AB	5,454,161	10/1995	Beilin et al.	29	852		
	AC	5,454,928	10/1995	Rogers et al.	205	125		
	AD	5,475,236	12/1995	Yoshizaki	257	48		
	AE	5,477,933	12/1995	Nguyen	174	262		
	AF	5,478,007	12/1995	Marrs	228	180.22		
	AG	5,483,421	01/1996	Gedney et al.	361	771		
	AH	5,484,647	01/1996	Nakatani et al.	428	209		
	AI	5,487,218	01/1996	Bhatt et al.	29	852		
	AJ	5,489,804	02/1996	Pasch	257	778		
	AK	5,493,096	02/1996	Koh	219	121.71		
↓	AL	5,508,229	04/1996	Baker	437	183		
	PD	AM	5,525,065	06/1996	Sobhani	439	67	
<b>Foreign Patent Documents</b>								
							<b>Translation</b>	
		Document	Date	Country	Class	Subclass	Yes	No
	AN							
	<del>AO</del>							
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AP	Ghaffarian, "Long Time BGA Assembly Reliability," Advancing Microelectronics, Vol. 25, No. 6, September/October 1998, pp. 20-23.						
PD	AQ	U.S. Application Serial No. 09/465,024, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Solder Via"						
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
PD	AA	5,536,973	07/1996	Yamaji	257	737		
	AB	5,542,601	08/1996	Fallon et al.	228	119		
	AC	5,547,740	08/1996	Higdon et al.	428	209		
	AD	5,556,810	09/1996	Fujitsu	437	209		
	AE	5,556,814	09/1996	Inoue et al.	437	230		
	AF	5,564,181	10/1996	Dineen et al.	29	841		
	AG	5,572,069	11/1996	Schneider	257	690		
	AH	5,576,052	11/1996	Arledge et al.	427	98		
	AI	5,583,073	12/1996	Lin et al.	439	183		
	AJ	5,595,943	01/1997	Itabashi et al.	437	230		
	AK	5,599,744	02/1997	Koh et al.	437	195		
	AL	5,611,140	03/1997	Kulesza et al.	29	832		
PD	AM	5,611,884	03/1997	Bearinger et al.	156	325		
<b>Foreign Patent Documents</b>								
							<b>Translation</b>	
		Document	Date	Country	Class	Subclass	Yes	No
	AN							
	AO							
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AP	U.S. Application Serial No. 09/464,562, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Strips And Via-Fill"						
PD	AQ	U.S. Application Serial No. 09/464,561, filed December 16, 1999, entitled "Bumpless Flip Chip Assembly With Strips-In-Via And Plating"						
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P17	AA	5,613,296	03/1997	Kurino et al.	29	852		
↓	AB	5,614,114	03/1997	Owen	219	121.66		
	AC	5,615,477	04/1997	Sweitzer	29	840		
	AD	5,619,791	04/1997	Lambrecht Jr. et al.	29	852		
	AE	5,627,405	05/1997	Chillara	257	668		
	AF	5,627,406	05/1997	Pace	257	700		
	AG	5,633,204	05/1997	Tago et al.	438	614		
	AH	5,637,920	06/1997	Loo	257	700		
	AI	5,641,113	06/1997	Somaki et al.	228	180.22		
	AJ	5,645,628	07/1997	Endo et al.	106	1.23		
	AK	5,646,067	07/1997	Gaul	437	180		
↓	AL	5,648,686	07/1997	Hirano et al.	257	778		
P17	AM	5,654,584	08/1997	Fujitsu	257	666		
<b>Foreign Patent Documents</b>								
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PD	AA	5,656,858	08/1997	Kondo et al.	257	737		
	AB	5,663,598	09/1997	Lake et al.	257	737		
	AC	5,665,652	09/1997	Shimizu	438	127		
	AD	5,666,008	09/1997	Tomita et al.	257	778		
	AE	5,669,545	09/1997	Pham et al.	228	1.1		
	AF	5,674,785	10/1997	Akram et al.	437	217		
	AG	5,674,787	10/1997	Zhao et al.	437	230		
	AH	5,682,061	10/1997	Khandros et al.	257	666		
	AI	5,691,041	11/1997	Frankeny et al.	428	209		
	AJ	5,722,162	03/1998	Chou et al.	29	852		
	AK	5,723,369	03/1998	Barber	438	106		
	AL	5,731,223	03/1998	Padmanabhan	437	183		
PD	AM	5,736,456	04/1998	Akram	438	614		
<b>Foreign Patent Documents</b>								
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<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
PD	AA	5,739,585	04/1998	Akram et al.	257	698		
↑	AB	5,744,859	04/1998	Ouchida	257	668		
	AC	5,757,071	05/1998	Bhansali	257	697		
	AD	5,757,081	05/1998	Chang et al.	257	778		
	AE	5,764,486	06/1998	Pendse	361	774		
	AF	5,774,340	06/1998	Chang et al.	361	771		
	AG	5,789,271	08/1998	Akram	438	18		
	AH	5,798,285	08/1998	Bentlage et al.	438	108		
	AI	5,801,072	09/1998	Barber	438	107		
	AJ	5,801,447	09/1998	Hirano et al.	257	778		
	AK	5,803,340	09/1998	Yeh et al.	228	56.3		
	AL	5,804,771	09/1998	McMahon et al.	174	255		
	AM	5,808,360	09/1998	Akram	257	738		
PD								
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PD	AA	5,811,879	09/1998	Akram	257	723		
↑	AB	5,817,541	10/1998	Averkiou et al.	438	107		
	AC	5,822,856	10/1998	Bhatt et al.	29	832		
	AD	5,834,844	11/1998	Akagawa et al.	257	734		
	AE	5,861,666	01/1999	Bellaar	257	686		
	AF	5,863,816	01/1999	Cho	438	123		
	AG	5,870,289	02/1999	Tokuda et al.	361	779		
	AH	5,883,435	03/1999	Geffken et al.	257	758		
	AI	5,925,931	07/1999	Yamamoto	257	737		
	AJ	5,994,222	11/1999	Smith et al.	438	689		
✓	AK	6,012,224	01/2000	DiStefano et al.	29	840		
✓	AL	6,013,877	01/2000	Degani et al.	174	264		
PD	AM	6,018,196	01/2000	Noddin	257	777		
<b>Foreign Patent Documents</b>								
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	AN							
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PD	AA	6,020,561	02/2000	Ishida et al.	174	261		
	AB	6,037,665	03/2000	Miyazaki	257	773		
	AC	6,046,909	04/2000	Joy	361	748		
	AD	6,084,297	06/2000	Brooks et al.	257	698		
	AE	6,084,781	07/2000	Klein	361	771		
	AF	6,103,552	08/2000	Lin	438	113		
	AG	6,103,992	08/2000	Noddin	219	121.71		
PD	AH	6,127,204	10/2000	Isaacs et al.	438	106		
	AI							
	AJ							
	AK							
	AL							
	AM							
<b>Foreign Patent Documents</b>								
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PD	AA	4,442,967	04/1984	van de Pas et al.	228	159		
	AB	4,661,192	04/1987	McShane	156	292		
	AC	4,717,066	01/1988	Goldenberg et al.	228	179		
	AD	4,750,666	06/1988	Neugebauer et al.	228	160		
	AE	4,807,021	02/1989	Okumura	357	75		
	AF	4,925,083	05/1990	Farassat et al.	228	102		
	AG	4,937,653	06/1990	Blonder et al.	357	68		
	AH	5,014,111	05/1991	Tsuda et al.	357	68		
	AI	5,060,843	10/1991	Yasuzato et al.	228	179		
	AJ	5,090,119	02/1992	Tsuda et al.	29	843		
	AK	5,172,851	12/1992	Matsushita et al.	228	179		
	AL	5,294,038	03/1994	Nakano et al.	228	179.1		
PD	AM	5,364,004	11/1994	Davidson	228	1.1		
<b>Foreign Patent Documents</b>								
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PD	AA	5,485,949	01/1996	Tomura et al.	228	180.5		
↑	AB	5,686,353	11/1997	Yagi et al.	437	183		
↓	AC	5,813,115	09/1998	Misawa et al.	29	832		
↓	AD	6,017,812	01/2000	Yonezawa et al.	438	613		
↓	AE	6,088,236	07/2000	Tomura et al.	361	783		
PD	AF	6,159,770	12/2000	Tetaka et al.	438	112		
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
	AM							
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	AA							
<b>Foreign Patent Documents</b>								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
	AB							
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AC	U.S. Application Serial No. 09/120,408, filed July 22, 1998, entitled "Flip Chip Assembly With Via Interconnection"						
	AD	U.S. Application Serial No. 09/643,212, filed August 22, 2000, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint"						
	AE	U.S. Application Serial No. 09/643,214, filed August 22, 2000, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint"						
	AF	U.S. Application Serial No. 09/643,213, filed August 22, 2000, entitled "Method Of Making A Support Circuit For A Semiconductor Chip Assembly"						
	AG	U.S. Application Serial No. 09/643,445, filed August 22, 2000, entitled "Method Of Making A Semiconductor Chip Assembly"						
	AH	U.S. Application Serial No. 09/665,928, filed September 20, 2000, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint"						
	AI	U.S. Application Serial No. 09/665,931, filed September 20, 2000, entitled "Method Of Making A Support Circuit With A Tapered Through-Hole For A Semiconductor Chip Assembly"						
PD	AJ	U.S. Application Serial No. 09/677,207, filed October 2, 2000, entitled "Method Of Making A Semiconductor Chip Assembly With A Conductive Trace Subtractively Formed Before And After Chip Attachment"						
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		Document	Date	Country	Class	Subclass	Yes	No
<del>AB</del>								
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
PD	AC	U.S. Application Serial No. 09/865,367, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint"						
PD	AD	U.S. Application Serial No. 09/864,555, filed May 24, 2001, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint"						
PD	AE	U.S. Application Serial No. 09/864,773, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint"						
Examiner PHUC T. DANG			Date Considered 4/13/05					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your next communication to Applicant.								